



1 **Bulk Grain Resistivity of ZnO-Based Varistors**

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6 **Abstract.** We study the temperature dependence of grain resistivity in ZnO ceramic varistors (300–430 K),  
 7 finding a positive temperature coefficient (PTC). We devise a high-frequency procedure that allow us to obtain  
 8 the concentration and energy position of the shallow donor. The observed behavior is consistent with a shallow  
 9 donor approaching complete ionization, and with an electron mobility mainly controlled by lattice (both optical  
 10 and acoustical) scattering. The impact of this behavior on varistor performance under high-current pulse loads is  
 11 discussed.

12 **Keywords:**

13 **1. Introduction**

14 Polycrystalline semiconductors with electrically ac-  
 15 tive interfaces are interesting from the fundamental  
 16 and technological points of view [1]. Their nonlinear  
 17 charge transport properties strongly depend upon the  
 18 electronic structure of the three different microscopic  
 19 regions within each grain [1–3]. (1) the interface or  
 20 grain boundary (GB), characterized by the existence of  
 21 a surface density of states; (2) the depletion layer (DL),  
 22 characterized by the presence of deep levels, which are  
 23 usually described by their concentration, energy po-  
 24 sition, and capture cross section; (3) and, finally, the  
 25 bulk grain region, characterized by the presence of a  
 26 shallow donor (responsible for the *n*-type conductiv-  
 27 ity of ZnO), which is described by its density  $N_0$  and  
 28 energy position  $\xi_0$ . A correct understanding of bulk-  
 29 grain-related phenomena is important in ceramic over-  
 30 voltage protection devices because grain resistivity is  
 31 closely related to high-field performance [4–6], and in  
 32 applications of polycrystalline semiconductors as mi-  
 33 crowave materials [1, 7], because bulk-grain properties  
 34 control the high frequency response. In the particular  
 35 case of ZnO, the study of the physics and chemistry of

the shallow donor is a very active research topic due 36  
 to its implications in spintronics [8], transparent con- 37  
 ductors, gas sensors, varistors, and optoelectronics [9]. 38  
 Despite this relevance, bulk grain properties of ceramic 39  
 semiconductors have not received much attention, and 40  
 shallow donor spectroscopic techniques based in the 41  
 analysis of the electrical response of a ceramic sample 42  
 have not been developed. In the case of ZnO varistors, a 43  
 few works have been published where suitable electri- 44  
 cal measurements directly yield grain resistivity [4, 5], 45  
 and an infrared reflectance technique [6], was proposed 46  
 that indirectly measures free-electron density and then 47  
 converts it into grain resistivity. 48

In this work, we develop an spectroscopic technique 49  
 that yields the concentration and thermal activation en- 50  
 ergy of a shallow donor in the grain interiors of ceramic 51  
 semiconductors. Then, we present the positive temper- 52  
 ature coefficient of resistivity (PTCR) of the bulk grains 53  
 of ZnO-based varistor ceramics, and discuss its im- 54  
 plications on varistor performance under high current 55  
 pulse loads. 56

2. Theoretical Background 57

At zero applied field, the conditions for electrical mea- 58  
 surements to yield meaningful information about grain 59  
 interiors can be understood through the broadband 60

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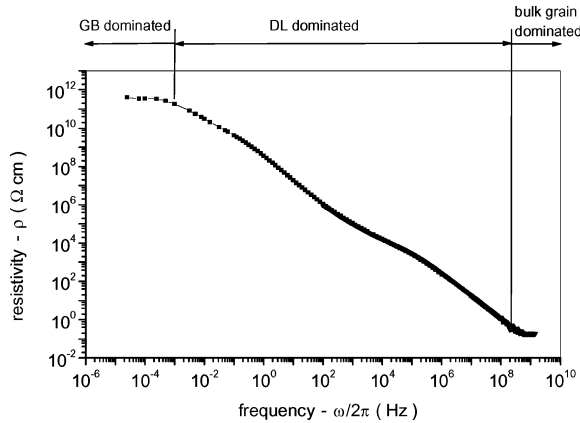


Fig. 1. Series resistivity measured over a very broad spectral range and showing clear convergence at the high-frequency limit, when the interfaces and depletion layers are shorted through the high frequency capacitance.

61 electrical response of Fig. 1. Close to the dc limit,  
 62 charge transport is dominated by thermionically emit-  
 63 ted over-barrier currents [1, 2], and the dc resistance  
 64 presents a well known negative temperature coeffi-  
 65 cient (NTC) due to the temperature dependence of the  
 66 thermionic current. Upon increasing frequency, the di-  
 67 electric response of the material takes control of its  
 68 electrical properties, and the real part of the impedance  
 69 becomes a meaningless parameter in itself, devoid of  
 70 a clear physical meaning, through more than ten or-  
 71 ders of magnitude in frequency. Finally, as soon as  
 72 the capacitance ( $C_p = Im(Y^*)/\omega$ ) of the material con-  
 73 verges to its high-frequency value [10], the control of  
 74 the transport properties moves to the bulk grain region  
 75 and the bulk grain resistance emerges, turning the sys-  
 76 tem into a series  $R_G-C_{HF}-L$  combination. The test for  
 77 the system to have reached its high frequency limit  
 78 is the convergence of the real part of the impedance,  
 79 which has no reason to converge to anything unless  
 80 the high frequency limit has been actually reached  
 81 (with the GBs shorted through the high frequency ca-  
 82 pacitance), in whose case it converges to the grain  
 83 resistance.

84 **3. Experiment**

85 Up to this point, the discussion is generally valid for any  
 86 polycrystalline semiconductor. We now focus in ZnO-  
 based varistors. Electrical measurements up to 1 GHz

were performed on rod-shaped samples  $\varnothing 1.5$  and 4 mm  
 long, machined to this size in order to delay the onset  
 of the geometrical resonance [5], and to ensure com-  
 plete penetration of the electromagnetic measuring sig-  
 nal [11, 12]. Samples were taken from commercial-  
 grade, high voltage (3 kV-rated, 3.33 kV/cm residual  
 voltage at 0.8 kA/cm<sup>2</sup>) ZnO varistors.  $R_G$  values have  
 been converted to  $\Omega \times cm$  by using microstructural  
 information about the percentage of secondary phases  
 in a polished, chemically etched cross-section of the  
 varistor material (approximately 6%). The experiments  
 were performed by placing the sample on a radio-  
 frequency commercial bridge, and heating the sample  
 with a computer controlled system. At each tempera-  
 ture, the high-frequency response in the range  $10^8-10^9$   
 Hz was recorded and convergence of the series resis-  
 tivity, such as that shown in Fig. 1, was verified. The  
 bulk grain resistivity of the sample was taken to be that  
 value attained at 1 GHz. Finally, high field measure-  
 ments were performed on samples of  $\varnothing 2.5$  and 3 cm  
 thick, with the aid of a specifically designed capacitor-  
 bank circuit.

4. Results and Discussion

The experimental points of Fig. 2 constitute our main  
 experimental result. We find a small but well defined  
 positive temperature coefficient (PTC) for the bulk

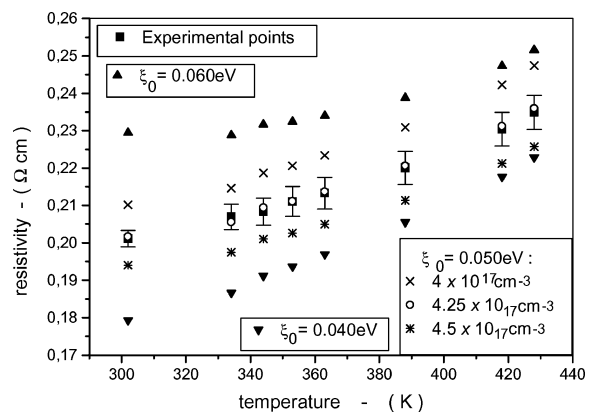


Fig. 2. Bulk PTC behavior in a typical ZnO-based varistor. The figure shows the experimental points, along with calculated curves corresponding to  $\xi_0 = 0.05$  eV and three different values of  $N_0$  (the total shallow donor density). Two additional curves correspond to fixed  $N_0 = 4.25 \times 10^{17} cm^{-3}$  and  $\xi_0 = 0.04/0.06$  eV.

113 grain resistivity: the grain interiors are found to be-  
 114 have in a metallic-like way. To explain this result, we  
 115 first write the grain resistivity  $\rho_G$  as

$$\rho_G = 1/(n\mu e), \quad (1)$$

116 where  $n$  and  $\mu$  are the free carrier density and mobil-  
 117 ity in the grains. Before proceeding further, we need  
 118 to clarify to what extent can we compare our high-  
 119 frequency  $\rho_G$  values, with those calculated from the  
 120 intrinsically dc Eq. (1). To this end, we use a simplified  
 121 treatment of charge carrier inertia [13] that has been  
 122 successfully applied to the high-frequency analysis of  
 123 GaAs Schottky diodes [14, 15]: free carrier conduc-  
 124 tion in a semiconductor is represented by a complex  
 125 conductivity

$$\sigma = \sigma_0/(1 + i\omega\tau) \quad (2)$$

126 where  $\sigma_0 = n\mu e$  is the dc conductivity,  $\tau = \mu m^*/e$   
 127 is the average free carrier relaxation time [13], and  $m^*$   
 128 is the free carrier effective mass. Hence, carrier inertia  
 129 effects are negligible when  $\omega\tau \ll 1$ ; introducing ap-  
 130 propriate values for ZnO at room temperature [16–18]  
 131 ( $m^* = 0.27m_0$  and  $\mu = 140 \text{ cm}^2/\text{Vs}$ ), this condition  
 132 implies  $\omega \ll 4 \times 10^{13} \text{ Hz}$ . Therefore, the electrical  
 133 conductivity of bulk ZnO remains very close to its dc  
 134 value up to the THz range, and we can safely com-  
 135 pare our experimental results with the  $\rho_G$  values to be  
 136 calculated through Eq. (1). To do so, we note that re-  
 137 ported [16–18] ZnO mobility-vs.-temperature curves  
 138 for a wide range of doping conditions, converge above  
 139 room temperature due to the dominance of lattice over  
 140 impurity scattering. Hence, we can select a reported  
 141  $\mu$ - $T$  curve [18] and, for each temperature, directly in-  
 142 troduce the experimental mobility values in Eq. (1).  
 143 Now, as thermodynamic calculations have shown that  
 144 room temperature charge balance within varistor ZnO  
 145 grains is maintained between electrons in the conduc-  
 146 tion band and ionized shallow donors [19], we can write  
 147 the charge balance equation as

$$n = N_C e^{-\xi/k_B T} = \frac{N_0}{1 + 2 \exp[(\xi_0 - \xi)/k_B T]}, \quad (3)$$

148 where  $n$  is the free carrier density,  $N_C$  is the con-  
 149 duction band effective density of states and  $\xi$  is the  
 150 Fermi level. At each fixed temperature, and assuming

a particular value for  $\xi_0$  and  $N_0$  in Eq. (3), we can  
 solve it for  $\xi$  and  $n$ , therefore calculating the quan-  
 tity  $1/n\mu e$ . Hence, corresponding to particular values  
 of  $\xi_0$  and  $N_0$ , we can obtain a calculated  $\rho_G$  vs.  $T$   
 to be compared with the experimental one. Figure 2  
 shows how the value of  $\xi_0$  controls the shape of the  
 calculated  $\rho_G$  vs.  $T$  curve, while  $N_0$  controls its re-  
 lative height with respect to the vertical axis. For a  
 given experimental  $\rho_G$  vs.  $T$  curve, one can find only  
 one couple ( $\xi_0, N_0$ ) that accurately reproduces exper-  
 iment. The values we have found are  $\xi_0 = 0.05 \text{ eV}$   
 and  $N_0 = 4.25 \times 10^{17} \text{ cm}^{-3}$ . The corresponding free  
 carrier density is  $n = 2.3 \times 10^{17} \text{ cm}^{-3}$  at room tem-  
 perature, in agreement with values obtained from re-  
 flectance measurements [6]. We then conclude that,  
 at room temperature and above, a shallow donor ap-  
 proaching complete ionization and a lattice-scattering  
 controlled mobility, render a PTC for the bulk-grain  
 resistivity. This PTC feature could explain the results  
 obtained in Ref. 20 by Modine et al., who found that  
 current amplitude decreased with successive current  
 pulse applications: here, the behavior of the sample  
 is bulk-grain dominated due to the barrier-suppressing  
 applied field, and Joule heating of the samples could  
 manifest itself in an increase of grain resistance, leading  
 to currents that decrease for constant applied voltage  
 [20]. This type of behavior is important for varistor sta-  
 bility under typical pulse and multi-pulse current test-  
 ing, as prescribed by international standards [21]. To  
 obtain independent verification of this high-field PTC  
 behavior, we have performed a series of pulsed-current  
 high field measurements. Samples were subjected to  
 $10^3 \text{ A/cm}^2$  high current pulses in order to drive them as  
 close as possible to the high-field ohmic region of their  
 I-V characteristic [4, 5], without degrading or breaking  
 them. Figure 3(a) presents one such a pulse, to be com-  
 pared with that of Fig. 3(b), corresponding to a much  
 smaller current density of  $25 \text{ A/cm}^2$ , which still shows  
 a very clear non-ohmic behavior. Samples were self-

Table 1. Values extracted from the high-field measurements of Fig. 3. Sample temperature increases due to self-heating, and sample resistance increases with sample temperature.

Pulse #	Sample resistance (mΩ)	Surface temperature before/after pulse (K)
1	170 ± 5	300/325
2	187 ± 5	336/349
3	201 ± 5	359/371

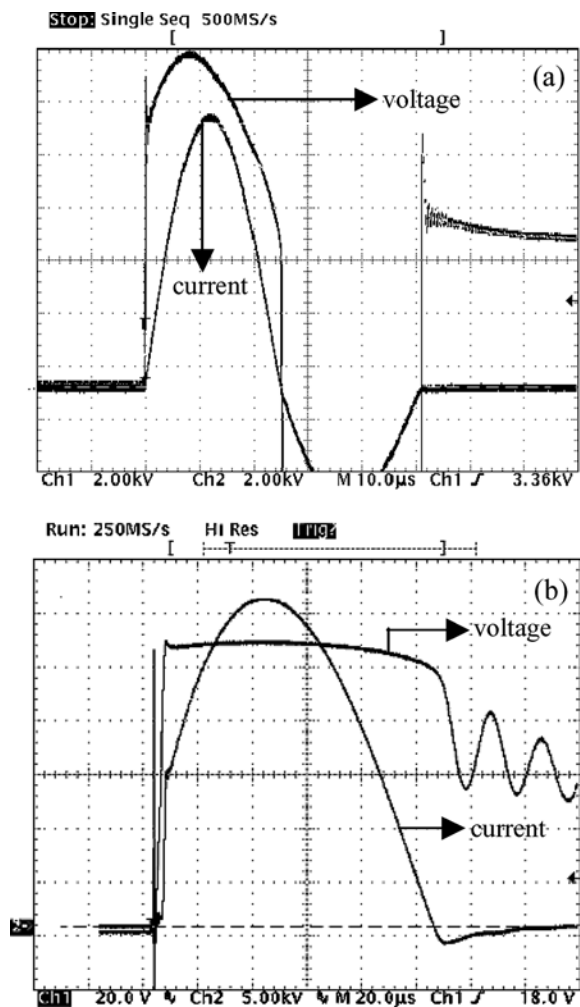


Fig. 3. High field measurements supporting a high field PTC behavior in a typical ZnO-based varistor. Figure 3(a) corresponds to a 20 kA current pulse, with the electrical response approaching a high-field ohmic behavior. Figure 3(b) corresponds to a 500 A current pulse, and the electrical response is clearly non-ohmic.

190 heated due to high current flow. Surface temperature  
 191 was recorded 0.5 s before and 0.5 s after each pulse.  
 192 Table 1 presents the relevant parameters obtained from  
 193 a sequence of three pulses such as the one in Fig. 3(a),  
 194 separated by a 3 s lapse. Peak values of the current and  
 195 voltage traces were used to evaluate sample resistance.  
 196 Note that reliable resistivity data can not be obtained  
 197 in the high field regime due to current constriction [5],  
 198 but the increase of resistance with sample tempera-  
 199 ture is clear and consistent with the high frequency  
 200 data.

## 5. Conclusions

We have devised a technique which allows to obtain the concentration and energy level of the shallow donor in polycrystalline *n*-doped ZnO. As an application, we have shown that ZnO-based varistor materials exhibit a transition from NTC to PTC behavior, as the control of the electrical properties changes from the interface/depletion-layer regions to the bulk grain region. The NTC/PTC cross-over can be defined either by a high enough frequency such that the material reaches its geometrical capacitance, or by an applied field that suppresses the grain boundary electrostatic barriers. We have shown that this PTC behavior explains relevant features of the pulse behavior of varistor devices.

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